

REMARKS

The above amendments have been made to present a preferred scope of coverage and not for reasons related to patentability.

Attached hereto is a marked-up version of the changes made to the claims by the current Preliminary Amendment. The attached page is captioned "**Version with Markings to Show Changes Made**".

Respectfully submitted,

Junichiro YOSHIOKA et al.

By: _____



Nils E. Pedersen

Registration No. 33,145

Attorney for Applicants

NEP/krl
Washington, D.C. 20006-1021
Telephone (202) 721-8200
Facsimile (202) 721-8250
May 15, 2002

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

**Version with Markings to
Show Changes Made**

21. (Amended) a plating apparatus for forming a protruding electrode on a substrate having wiring formed thereon, comprising:

- a cassette table for loading a cassette housing the substrate therein;
- a plating tank for plating the substrate;
- a cleaning unit for cleaning the plated substrate;
- a drying unit for drying the cleaned substrate;
- a deaerating unit for deaerating a plating liquid [in the plating tank];
- a plating liquid regulating unit for analyzing the components of the plating liquid and adding components to the plating liquid based on the results of the analysis; and
- a substrate transferring device for transferring the substrate.

27. (Amended) The plating apparatus according to claim 26, further comprising [a drying unit for drying] a cleaning unit for cleaning the plated substrate taken out of said substrate holder.

35. (Amended) A plating apparatus for forming a protruding electrode on a substrate having wiring formed thereon, comprising:

- a cassette table for loading a cassette housing the substrate therein;
- a pre-wetting tank for applying a pre-wetting treatment to the substrate to increase the wettability thereof;
- a plating tank for plating the substrate after the pre-wetting treatment;
- a cleaning unit for cleaning the plated substrate;
- a drying unit for drying the cleaned substrate;
- a deaerating unit for deaerating a [plating] liquid used for the pre-wetting treatment [in the plating tank]; and
- a substrate transferring device for transferring the substrate.

40. (Amended) The plating apparatus according to claim 39, further comprising a [drying] cleaning unit for [drying] cleaning the plated substrate taken out of said substrate holder.

46. (Amended) An apparatus for forming a protruding electrode on a substrate having wiring formed thereon, comprising:

- a cassette table for loading a cassette housing the substrate therein;
- a pre-soaking tank for applying a pre-soaking treatment to the substrate;
- a plating tank for plating the substrate after the pre-soaking treatment;
- a cleaning unit for cleaning the plated substrate;
- a drying unit for drying the cleaned substrate;
- a deaerating unit for deaerating [the plating] a liquid [in the plating tank] used for the pre-soaking treatment; and
- a substrate transferring device for transferring the substrate.

51. (Amended) The plating apparatus according to claim [46] 50, further comprising a [drying] cleaning unit for [drying] cleaning the plated substrate taken out of said substrate holder.

62. (Amended) The plating apparatus according to claim 61, further comprising a [drying] cleaning unit for [drying] cleaning the plated substrate taken out of said substrate holder.

67. (Amended) An apparatus for forming a protruding electrode on a substrate having wiring formed thereon, comprising:

- a cassette table for loading a substrate cassette thereon;
- a plating tank for plating the substrate;
- a cleaning unit for cleaning the plated substrate;
- a drying unit for drying the cleaned substrate;
- a deaerating unit for deaerating a plating liquid [in the plating tank];
- an annealing unit for annealing the plated substrate; and
- a substrate transferring device for transferring the substrate.

70. (Amended) A method for forming a protruding electrode on a substrate having wiring formed thereon, comprising:

- holding a substrate taken out of a cassette by a substrate holder;

pre-wetting the substrate held by said substrate holder;
plating the pre-wetted surface of the substrate by immersing the substrate together with said substrate holder in a plating liquid;
cleaning [and drying] the plated substrate together with said substrate holder; and
taking the substrate out of said substrate holder and drying the substrate.

71. (Amended) A method for forming a protruding electrode on a substrate having wiring formed thereon, comprising:

holding a substrate taken out of a cassette by a substrate holder;
pre-soaking the substrate held by said substrate holder;
plating the pre-soaked surface of the substrate by immersing the substrate together with said substrate holder in a plating liquid;
cleaning [and drying] the substrate together with said substrate holder; and
taking the substrate out of said substrate holder and drying the substrate.